



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-05-08
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LM2904YST	EBE3*0158BI6	A	ZY1A	2013-05-08
Amount		UoM	Unit type	ST ECOPACK Grade
25.081		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	ium/Gold (Ni/Pd/Au) Tin/Bismuth (S	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	3X3X0.86	8	gull wing	
Comment	Package: MSOP/TSSOP 8 BODY3.00 PITCH0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EBE3*0158B16					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	0.705	mg		Die	Silicon (Si)	7440-21-3		0.705	mg	1000000	28109
LEADFRAME	Copper & its alloys	12.044	mg		Alloy	Copper (Cu)	7440-50-8		11.356	mg	942876	452773
LEADFRAME					Alloy	Nickel (Ni)	7440-02-0		0.354	mg	29392	14114
LEADFRAME					Alloy	Silicon (Si)	7440-21-3		0.077	mg	6393	3070
LEADFRAME					Alloy	Magnesium (Mg)	7439-95-4		0.018	mg	1495	718
LEADFRAME					Plating	Nickel (Ni)	7440-02-0		0.233	mg	19346	9290
LEADFRAME					Plating	Palladium (Pd)	7440-05-3		0.005	mg	415	199
LEADFRAME					Plating	Gold (Au)	7440-57-5		0.001	mg	83	40
DIE ATTACH	Other Organic Materials	0.405	mg		Glue	Epoxy Resin A	Proprietary		0.028	mg	69136	1116
DIE ATTACH					Glue	Epoxy Resin B	Proprietary		0.016	mg	39506	638
DIE ATTACH					Glue	Silver (Ag)	7440-22-4		0.313	mg	772840	12480
DIE ATTACH					Glue	Lactone	96-48-0		0.016	mg	39506	638
DIE ATTACH					Glue	Polyoxypropylenediamine	9046-10-0		0.016	mg	39506	638
DIE ATTACH					Glue	2,6 Diglycidyl phenyl allyl ether oligomer	Proprietary		0.016	mg	39506	638
BONDING WIRE	Precious metals	0.09	mg		Bonding wire	Gold (Au)	7440-57-5		0.09	mg	1000000	3588
ENCAPSULATION	Other Organic Materials	11.837	mg		Molding compound	Multi-aromatic resin	Proprietary		1.065	mg	89972	42462
ENCAPSULATION					Molding compound	Silica, vitreous	60676-86-0		9.944	mg	840078	396475
ENCAPSULATION					Molding compound	Phenol Resin	Proprietary		0.769	mg	64966	30661
ENCAPSULATION					Molding compound	Carbon Black	1333-86-4		0.059	mg	4984	2352